

Art Unit: 2800

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1. (currently amended) A chip scale package suitable for use in a radio-frequency (RF)-range electronic device comprising:

a leadframe including at least (1) a die attach pad located thereon for connection directly to a circuit board board, and (2) a plurality of wire bonding pads peripherally located thereon, and (3) at least one aperture formed fully through said the die attach pad to separate said the die attach pad into different sections;

at least one die having a first surface and an opposing second surface and being mounted on a section of said the die attach pad such that substantially the entire opposing second surface is contacta said in-mated-contact with the die attach pad, thereby forming a grounding path which is confined to said section and leads from said at least one die, through said section section, and to said circuit board;

at least one bonding wire for electrically connecting the said at least one die and at least one of said the plurality of wire bonding pads; and

a mold compound, wherein said mold compound encapsulates said the at least one die and said the at least one bonding wire to form a chip scale package, and wherein the mold compound resides in said the at least one aperture.

4. (currently amended) The chip package of claim 1, wherein said the aperture is formed using a full etch process.

5. (currently amended) The chip package of claim 1, wherein the shape of said the aperture is one of the following: a rectangle, a square, an oval, a triangle, a circle, or a combination thereof.

6. (original) The chip package of claim 1, wherein the chip package is a leadframe-based Chip Scale Package.

7. (currently amended) The chip package of claim 1, wherein said the aperture includes a plurality of apertures formed around said the at least one die.

8. (currently amended) The chip package of claim 7, wherein said the at least one die comprises at least a first and a second die, and at least one of said the plurality of apertures is disposed between said the first die and said the second die.

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19. (currently amended) A method for improving radio frequency grounding in a high dynamic range electronic device comprising operating a chip scale package at radio frequency (RF), said chip scale package comprising:

a leadframe including at least (1) a die attach pad located thereon for connection directly to a circuit board, and (2) a plurality of wire bonding pads peripherally located thereon, and (3) at least one aperture formed fully through said die attach pad to separate said die attach pad into different sections;

at least one die having a first surface and an opposing second surface and being mounted on a section of said die attach pad such that substantially the entire

opposing second surface is contacts said in-mated-contact with the die attach pad, thereby forming an RF grounding path which is confined to said section and leads from said at least one die, through said section, and to said circuit board;

at least one bonding wire for electrically connecting said the at least one die and at least one of said the plurality of wire bonding pads; and

a mold compound, wherein said mold compound encapsulates said the at least one die and said the at least one bonding wire to form a chip scale package, and wherein the mold compound resides in said the at least one aperture.